

STB26NM60N, STP26NM60N

N-channel 600 V, 0.135 Ω typ., 20 A MDmesh™ II Power MOSFETs in D²PAK and TO-220 packages

Datasheet - production data

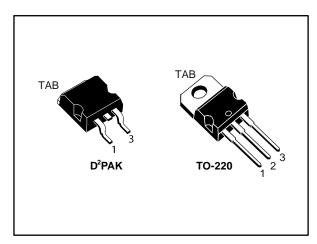
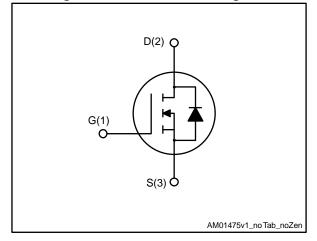


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max	ΙD
STB26NM60N	600 V	0.165 Ω	20 A
STP26NM60N	600 V	0.165 12	20 A

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

Applications

• Switching applications

Description

These devices are N-channel Power MOSFETs developed using the second generation of MDmesh™ technology. This revolutionary Power MOSFET associates a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. It is therefore suitable for the most demanding high efficiency converters.

Table 1: Device summary

Order code	Marking	Package	Packaging
STB26NM60N	OCNIMCONI	D²PAK	Tape and reel
STP26NM60N	26NM60N	TO-220	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage	600	V
V_{GS}	Gate-source voltage	±30	V
ΙD	Drain current (continuous) at T _C = 25 °C	20	Α
ΙD	Drain current (continuous) at T _C = 100 °C	12.6	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	80	Α
Ртот	Total dissipation at T _C = 25 °C	140	W
dv/dt (2)	Peak diode recovery voltage slope	15	V/ns
T _{stg}	Storage temperature range	FF to 1F0	°C
Tj	Operating junction temperature range	-55 to 150	

Notes:

Table 3: Thermal data

Symbol	Parameter		Value		
Symbol			TO-220	Unit	
R _{thj-case}	Thermal resistance junction-case	0.89		°C/W	
R _{thj-amb}	Thermal resistance junction-ambient	62.5		°C/W	
R _{thj-pcb} (1)	Thermal resistance junction-pcb	30		°C/W	

Notes

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AS}	Single pulse avalanche current (pulse width limited by T _{jmax})	6	Α
E _{AS}	Single pulse avalanche energy (starting T _J =25 °C, I _D =I _{AS} , V _{DD} =50 V)	610	mJ

⁽¹⁾Pulse width limited by safe operating area.

 $^{^{(2)}}I_{SD} \leq 20~A,~di/dt \leq 400~A/\mu s,~V_{DS(peak)} \leq V_{(BR)DSS},~V_{DD} = 80\%~V_{(BR)DSS}$

 $^{^{(1)}}$ When mounted on FR-4 board of 1inch², 2oz Cu, t < 10 s.

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 5: On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0 V	600			V
	Zaro goto voltago drain	V _{GS} = 0 V, V _{DS} = 600 V			1	
I _{DSS} Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V},$ $T_{C} = 125 ^{\circ}\text{C}^{(1)}$			100	μΑ	
Igss	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			±0.1	μΑ
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	3	4	V
R _{DS(on)}	Static drain-source on- resistance	V _{GS} = 10 V, I _D = 10 A		0.135	0.165	Ω

Notes:

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Ciss	Input capacitance		-	1800	-	pF
Coss	Output capacitance	$V_{DS} = 50 \text{ V}, f = 1 \text{ MHz},$	-	115	-	pF
C _{rss}	Reverse transfer capacitance	V _{GS} = 0 V		6	-	pF
Coss eq.	Equivalent output capacitance	V _{GS} = 0 V, V _{DS} = 0 to 480 V	-	310	-	pF
Qg	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 20 \text{ A},$	-	60	-	nC
Q_{gs}	Gate-source charge	V _{GS} = 10 V	-	8.5	-	nC
Q_{gd}	Gate-drain charge	(see Figure 14: "Test circuit for gate charge behavior"	-	30	-	nC
Rg	Gate input resistance	f=1 MHz, I _D =0 A	-	2.8	-	Ω

Notes:

 $^{(1)}C_{oss~eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}

⁽¹⁾Defined by design, not subject to production test.

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 10 \text{ A}, R_G = 4.7 \Omega,$	1	13	-	ns
tr	Rise time	V _{GS} = 10 V (see Figure 13: "Test circuit for	ı	25	1	ns
t _{d(off)}	Turn-off delay time	resistive load switching times" and		85	-	ns
t _f	Fall time	Figure 18: "Switching time waveform")	-	50	-	ns

Table 8: Source-drain diode

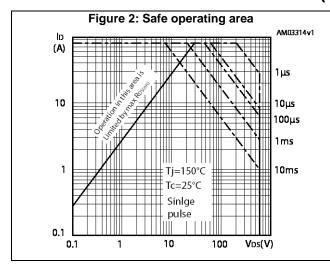
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		20	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		80	Α
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 20 A, V _{GS} = 0	-		1.5	V
t _{rr}	Reverse recovery time	I _{SD} = 20 A, di/dt = 100 A/μs	-	370		ns
Qrr	Reverse recovery charge	V _{DD} = 60 V (see Figure 15: "Test circuit for		5.8		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	-	31.6		Α
t _{rr}	Reverse recovery time	I _{SD} = 20 A, di/dt = 100 A/µs	-	450		ns
Q _{rr}	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 ^{\circ}\text{C}$ (see Figure 15: "Test circuit for	-	7.5		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	-	32.5		Α

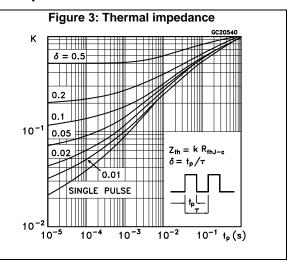
Notes:

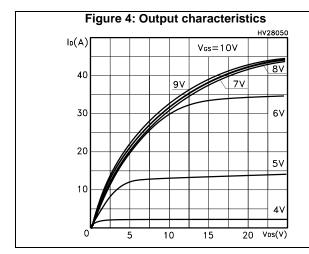
⁽¹⁾Pulse width limited by safe operating area.

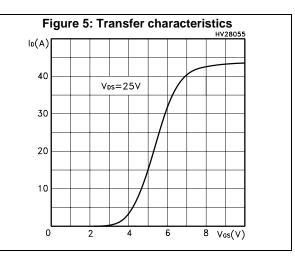
 $^{^{(2)}}$ Pulsed: pulse duration = 300 μ s, duty cycle 1.5%

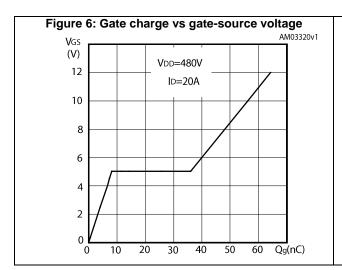
2.1 Electrical characteristics (curves)

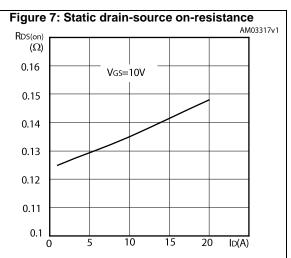












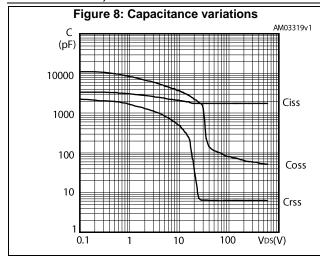
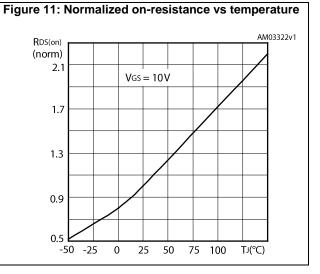
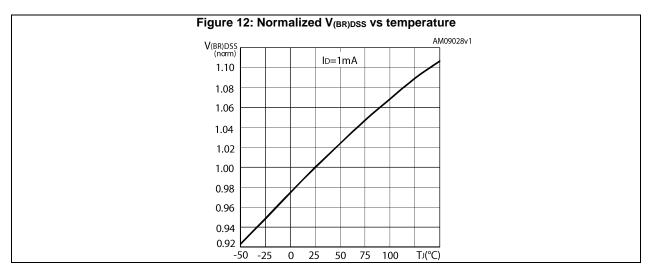


Figure 10: Normalized gate threshold voltage vs temperature AM03321v1 $V_{GS(th)}$ (norm) 1.1 $ID = 250 \,\mu A$ 1.0 0.9 0.8 0.7 -50 -25 50 75 100 0 25 TJ(°C)



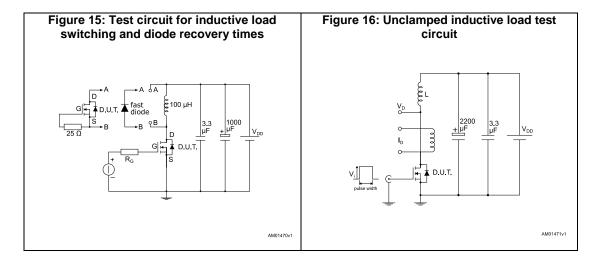


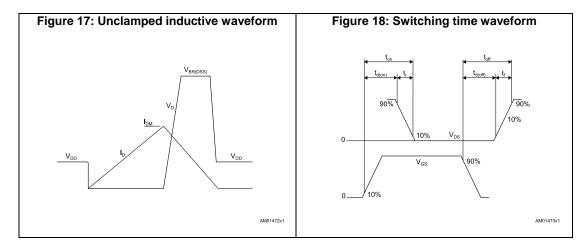
3 Test circuits

Figure 13: Test circuit for resistive load switching times

Figure 14: Test circuit for gate charge behavior

Figure 14: Test circuit for gate charge behavior





4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 D2PAK (TO-263) type A package information

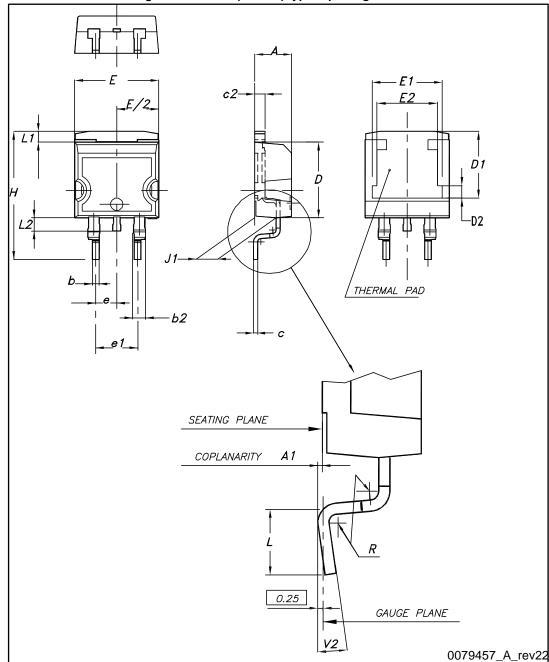
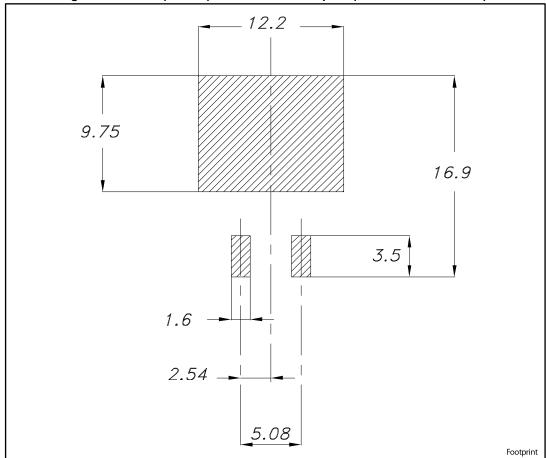


Figure 19: D²PAK (TO-263) type A package outline

Table 9: D²PAK (TO-263) type A package mechanical data

	bie 9. D-FAR (10-203) tyl	mm	
Dim.	Min.	Тур.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
С	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
е		2.54	
e1	4.88		5.28
Н	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 20: D²PAK (TO-263) recommended footprint (dimensions are in mm)



4.2 D2PAK packaging information

Figure 21: Tape outline

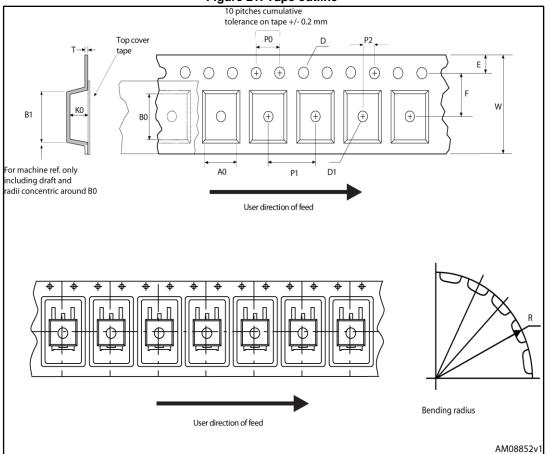


Figure 22: Reel outline

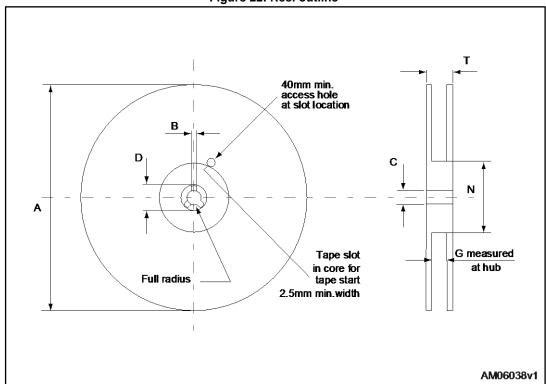


Table 10: D2PAK tape and reel mechanical data

Таре				Reel		
Dim.	n	nm	Dim.	mm		
Dim.	Min.	Max.	Dim.	Min.	Max.	
A0	10.5	10.7	А		330	
В0	15.7	15.9	В	1.5		
D	1.5	1.6	С	12.8	13.2	
D1	1.59	1.61	D	20.2		
E	1.65	1.85	G	24.4	26.4	
F	11.4	11.6	N	100		
K0	4.8	5.0	Т		30.4	
P0	3.9	4.1				
P1	11.9	12.1	Base q	uantity	1000	
P2	1.9	2.1	Bulk quantity 10		1000	
R	50					
Т	0.25	0.35				
W	23.7	24.3				

4.3 TO-220 type A package information

Figure 23: TO-220 type A package outline

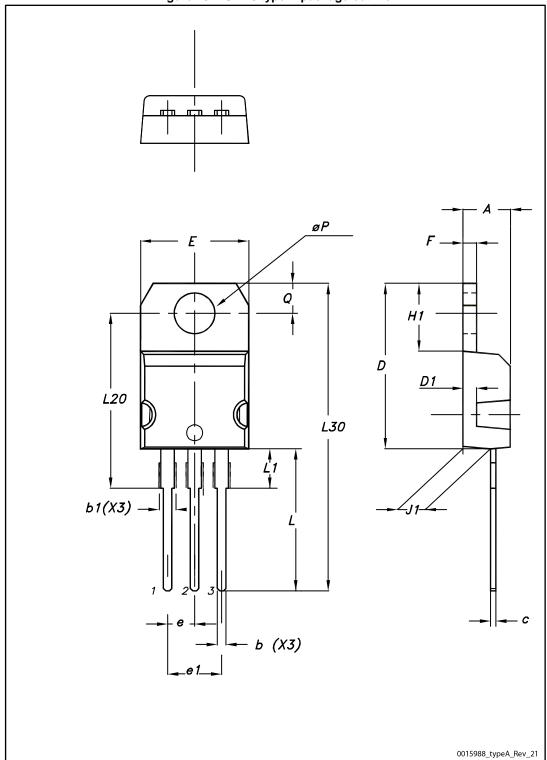


Table 11: TO-220 type A mechanical data

Dim.	mm		
	Min.	Тур.	Max.
А	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
С	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øΡ	3.75		3.85
Q	2.65		2.95

5 Revision history

Table 12: Document revision history

Date	Revision	Changes	
29-Apr-2009	1	First release.	
17-Dec-2009	2	Added new package, mechanical data: D2PAK	
20-Jun-2011	3	Inserted device in I²PAK.	
13-Mar-2012	4	Updated P _{TOT} and derating factor in <i>Table 2</i> . Update R _{thj-case} for TO-220FP in <i>Table 3</i> . Update <i>Figure 10</i> and <i>Figure 15</i> . Update <i>Section 5: Packaging mechanical data</i> .	
20-Jun-2012	5	Updated title on the cover page. Minor text changes.	
09-Sep-2013	6	 The part numbers STI26NM60N and STW26NM60N have been moved to the separate datasheets Modified: V_{GS} value in <i>Table 2</i>. 	
12-Dec-2016	7	The part number STF26NM60N has been moved to a separate datasheet. Modified Table 2: "Absolute maximum ratings", Table 3: "Thermal data", Table 5: "On/off states", Table 6: "Dynamic" and Table 7: "Switching times". Modified Section 2.1: "Electrical characteristics (curves)". Minor text changes.	

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